

# eries Wire Wound Molded SMD Power Inductors Size 25201B



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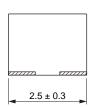
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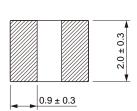
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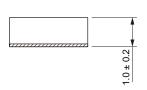
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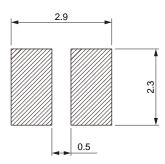
Dimensions: [mm]

Land Pattern: [mm]









Part No	Inductance @ 1MHz/1V (μΗ)	Tolerance	Saturation Current Typ. (A)	Saturation Current Max. (A)	Temperature Rise Current Typ. (A)	Temperature Rise Current Max. (A)	DC Resistance Max. (mΩ)

Saturation Current will cause L to drop approximately 30%

Temperature Rise Current: The actual value of DC current when the temperature rise is  $\triangle T$ =40°C



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698 640 618m

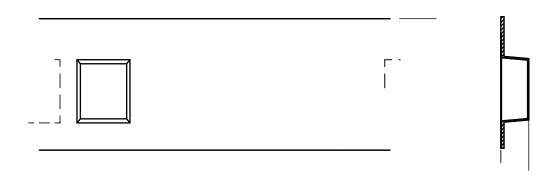
INDUCTANCE (uH)5158 640 618m36,286 D0 2f0q



# Soldering Reflow:

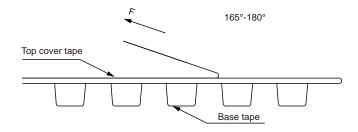
# Packaging Information:

Tape Dimension:



Series	A0	B0	D	P0	P1	W	K0	E	T
	(mm)	(mm)							
MDTE25201B	2.4±0.1	2.9±0.1	1.5±0.1	4.0±0.1	4.0±0.1	8.0±0.1	1.4±0.1	1.75±0.1	0.25±0.05

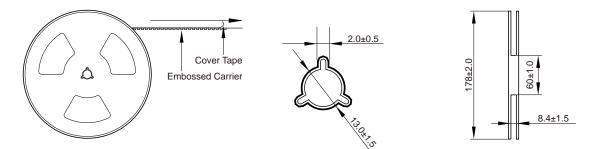
## Peel force of top cover tape:



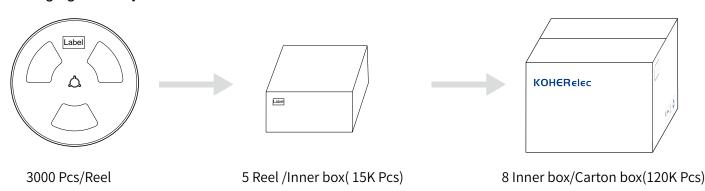
The peel force of top cover tape shall be between 0.1 to 0.98 N



### Reel Dimension: [mm]



#### Packaging Quantity:



## Storage Conditions:

Cautions and Warnings:

- The storage period is within 12 months after the completion of production. Be sure to follow the storage conditions (temperature: -5 to 35°C, humidity: 75% RH Max). If the storage period elapses, the soldering of the terminal electrodes may deteriorate. The warranty period is one year.
- Product should not be exposed to environment with high temperature, high humidity, dust, corrosive gas and etc.
- Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
- Please always handle products carefully to prevent any damage caused by dropping down or inappropriate removing.

#### **Operation Instructions:**

- Self heating (temperature increase) occurs when the power is turned ON, so the tolerance should be sufficient for the set thermal design.
- Before soldering, be sure to preheat components. The preheating temperature should be set so that the temperature difference between the solder temperature and chip temperature does not exceed 150°C.
- Soldering corrections after mounting should be within the range of the conditions determined in the specifications. If overheated, a short circuit, performance deterioration, or lifespan shortening may occur.
- Generally, Koher might not be familiar with either customer's specific application or actual requests as customer
  does.As a result customer shall be responsible for checking and confirming whether Koher product with the
  performance described in the product specification is suitable for using in customer's particular application or
  not.